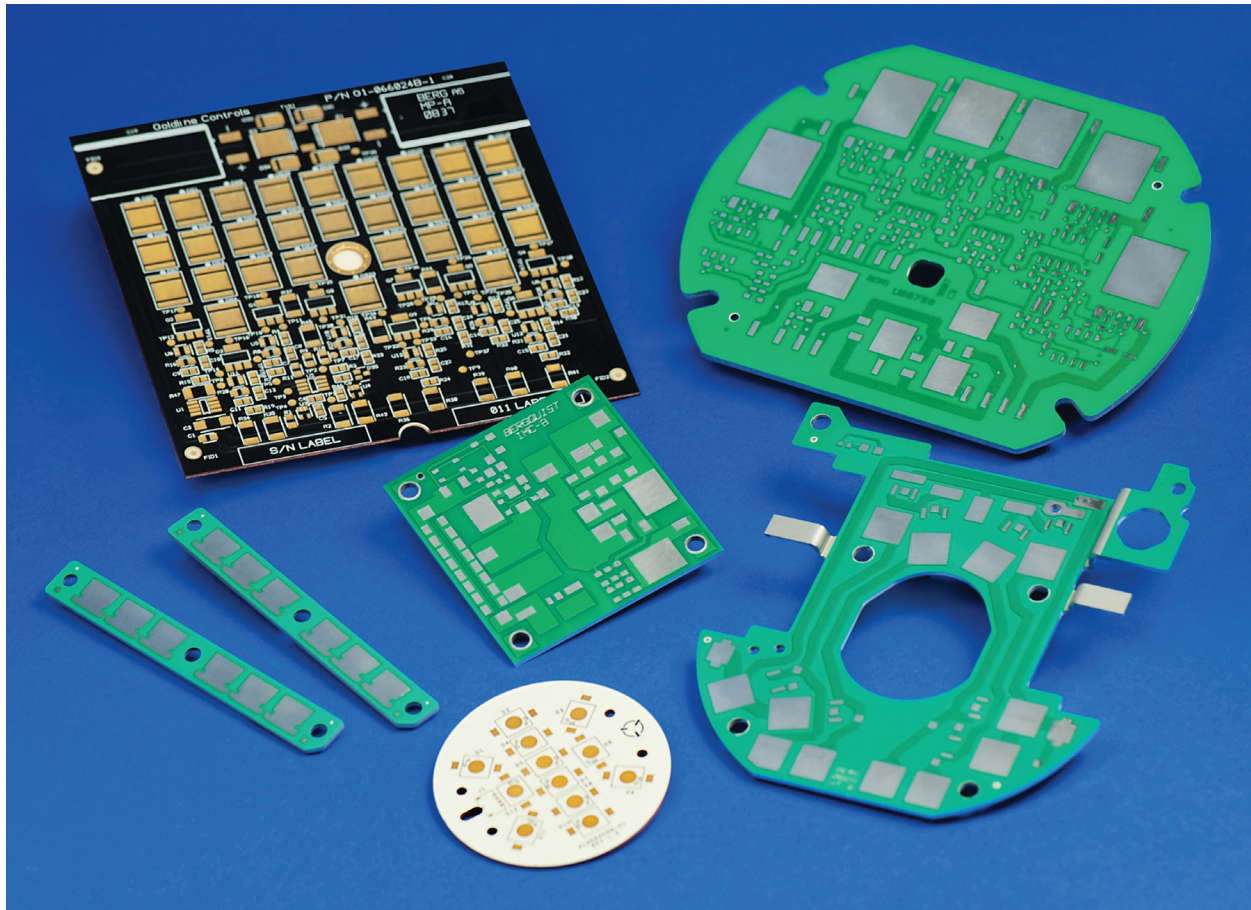




Benefits

- Thermal resistance $0.09^{\circ}\text{Cin}^2/\text{W}$ ($0.58^{\circ}\text{Ccm}^2/\text{W}$)
- Thermal conductivity of 2.4 W/m-K
- Multi-Purpose applications
- Lead-free solder compatible
- Eutectic AuSn compatible
- RoHS compliant and environmentally green
- Available on all aluminum and copper metal substrates

Thermal Clad Metal Core PCB's (MCPCB's) minimize thermal impedance and conduct heat more effectively than standard printed wiring boards (PWB's). These substrates are more mechanically robust than thick-film ceramic and direct bond copper construction.

Thermal Clad is a cost-effective solution which can eliminate components, allow for simplified designs, smaller devices and an overall less complicated production process. Additional benefits of Thermal Clad include lower operating temperatures, resulting in longer component life and increased durability.

The technology of Thermal Clad resides in the dielectric. This datasheet highlights the performance characteristics of Thermal Clad MP (Multi-Purpose), with twenty plus year's industry proven dielectric for a multitude of applications including LED, Power Conversion, Heat-Rails, Solid State Relays and Motor Drives.

MP Typical Values

MP-06503	VALUE	TEST METHOD
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THERMAL PROPERTIES

Product Thermal Conductivity	2.4 W/m-K	MET 5.4-01-40000
Dielectric Thermal Conductivity	1.3 W/m-K	ASTM D5470
Thermal Resistance	0.09°C-in²/W (0.58°C-cm²/W)	ASTM D5470
Thermal Impedance	0.65°C/W	MET-5.4-01-40000
Glass Transition	90°C	ASTM E1356
Max Operating Temp.	130°C	U.L. 796
Max Soldering Temp.	325°C	U.L. 796

ELECTRICAL PROPERTIES

Dielectric Constant	6	ASTM D150
Dissipation Factor	0.003/0.017 (@1KHz/1MHz)	ASTM D150
Capacitance	410 pF/in² (65pF/cm²)	ASTM D150
Volume Resistivity	1 ¹⁵ Ω-m	ASTM D257
Surface Resistivity	1 ¹⁴ Ω/sq	ASTM D257
Dielectric Strength	2800 V/mil (112 kV/mm)	ASTM D149
Breakdown Voltage	8.5 kVAC	ASTM D149

MECHANICAL PROPERTIES

Color	White	Visual
Dielectric Thickness	0.003" (76 μm)	Visual
Peel Strength@25C	9 lb/in (1.6 N/mm)	ASTM D2861
CTE in XY/Z Axis <T _g	40 μm/m°C	ASTM D3386
CTE in XY/Z Axis >T _g	110 μm/m°C	ASTM D3386
Storage Modulus	12/0.3 GPa (@25°C/150°C)	ASTM 4065

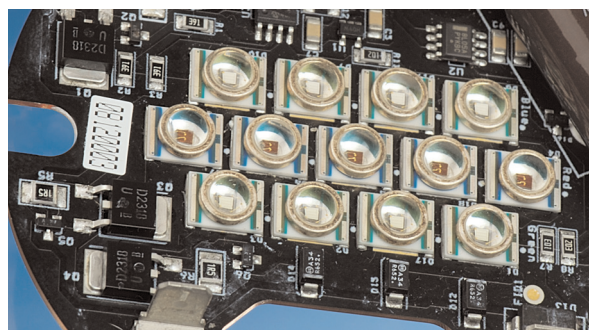
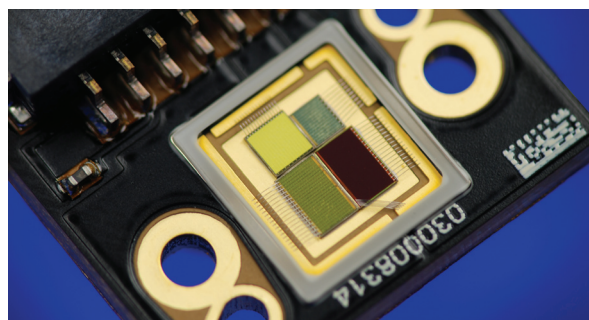
CHEMICAL PROPERTIES

Water Vapor Retention	0.21% wt.	ASTM E595
Out-Gassing Total Mass Loss	0.29% wt.	ASTM E595
Collect Volatile Condensable Material	0.01% wt.	ASTM E595

AGENCY RATINGS & DURABILITY

U.L. Maximum Operating Temperature	130°C	U.L. 746B
U.L. Flammability	V-0	U.L. 94
Comparative Tracking Index (CTI)	0/500 (425)	ASTM D3638/IEC60112
Solder Limit Rating	300°C/60 seconds	U.L. 796

Please test this material in your application. Bergquist provides this engineering data for design guidance only. Depending upon your application, the observed material performance may vary.



High Power LED applications using Thermal Clad.

Applications

- High watt-density applications where achieving low thermal resistance is required
- Power conversion
- Heat-rails
- Solid state relays
- Motor drives
- LED applications

MET-4.5-01-40000 Test Thermal Performance of Insulated Metal Substrates (IMS) TO-220 Set-up

